

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HIDEKI MAKIYAMA</td> <td>08/29/2012</td> </tr> <tr> <td>YOSHIKI YAMAMOTO</td> <td>08/29/2012</td> </tr> </tbody> </table>		Name	Execution Date	HIDEKI MAKIYAMA	08/29/2012	YOSHIKI YAMAMOTO	08/29/2012		
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RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>RENESAS ELECTRONICS CORPORATION</td> </tr> <tr> <td>Street Address:</td> <td>1753, Shimonumabe, Nakahara-ku, Kawasaki-shi</td> </tr> <tr> <td>City:</td> <td>Kanagawa</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	RENESAS ELECTRONICS CORPORATION	Street Address:	1753, Shimonumabe, Nakahara-ku, Kawasaki-shi	City:	Kanagawa	State/Country:	JAPAN
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PROPERTY NUMBERS Total: 1									
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CORRESPONDENCE DATA									
<p>Fax Number:</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 202-756-8000</p> <p>Email: mweipdocket@mwe.com</p> <p>Correspondent Name: MCDERMOTT WILL & EMERY LLP</p> <p>Address Line 1: 600 13TH STREET, N.W.</p> <p>Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20005-3096</p>									
ATTORNEY DOCKET NUMBER:	091566-0012								
NAME OF SUBMITTER:	Stephen A. Becker 26527 (mjb)								
<p>Total Attachments: 2</p> <p>source=ASSN_091566-0012#page1.tif</p> <p>source=ASSN_TRN_091566-0012#page1.tif</p>									

CH \$40.00 13620986

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by RENESAS ELECTRONICS CORPORATION, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said RENESAS ELECTRONICS CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND MANUFACTURING METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said RENESAS ELECTRONICS CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS ELECTRONICS CORPORATION,

Signed on the date(s) indicated aside signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1)	<u>Hideki MAKIYAMA (Hideki MAKIYAMA)</u>	<u>8/29/2012</u>
2)	<u>Yoshiki YAMAMOTO (Yoshiki YAMAMOTO)</u>	<u>8/29/2012</u>
3)	<u></u>	<u></u>
4)	<u></u>	<u></u>
5)	<u></u>	<u></u>
6)	<u></u>	<u></u>
7)	<u></u>	<u></u>

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

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